



Material Content Data Sheet



Sales Product Name		IPS80R600P7		Issued		31. July 2018		
MA#		MA001649844						
Package		PG-TO251-3-342		Weight*		318.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.758	0.87	0.87	8656	8656
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.16	46.22	461714	462315
	non noble metal	aluminium	7429-90-5	0.910	0.29	0.29	2855	2855
wire	non noble metal	aluminium	7429-90-5	0.910	0.29	0.29	2855	2855
encapsulation	organic material	carbon black	1333-86-4	1.406	0.44		4413	
	plastics	epoxy resin	-	24.604	7.72		77228	
	inorganic material	silicondioxide	60676-86-0	114.584	35.97	44.13	359664	441305
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11739	11739
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4459	4470
solder	non noble metal	tin	7440-31-5	0.053	0.02		168	
	noble metal	silver	7440-22-4	0.067	0.02		210	
	non noble metal	lead	7439-92-1	2.551	0.80	0.84	8009	8387
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60195	60273
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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